

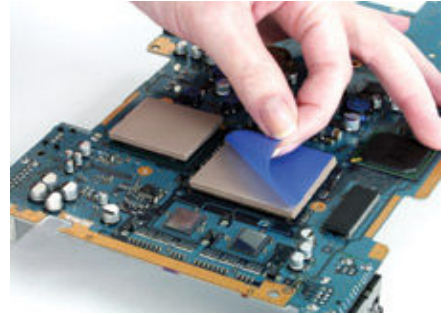
CSC THERMAL CONDUCTIVE PAD

TP-H2000 Series

Description & Applications

TP-H2000 is designed as a cost effective and high thermal conductive materials. The high thermal conductivity and mechanical properties allows the pads to apply to various electronic components. These applications also typically have low mounting pressures for component clamping.

- Chip Modules (Memory, Ceramic Component)
- High Power Components (Power Transistor)
- Power Transfer Devices



Main Features

- Thermal conductivity = 2.0 ~ 2.5 W/mK
- High thermal performance & cost effective solution
- Medium conformability
- Electrically insulating



Specifications

ITEM	TP-H2000	METHOD
Mechanical		
Color*	Pink	Visual
Thickness (mm)	0.1 ~ 5.0	ASTM D374
Density (g/cc)	1.98	ASTM D792
Hardness (Shore A)	54	ASTM D2240
Tensile Strength (kgf/cm ²)	27.2	ASTM D412
Use Temp. (°C)	-60 ~ 200	-
Electrical		
Dielectric Breakdown Voltage (V)	> 6,000	ASTM D149
Volume Resistivity (Ω · cm)	10 ¹³	ASTM D257
Thermal		
Thermal Conductivity (W/mK)	2.0	ASTM C518-98 (Modified)
Flame Rating (UL94)	V-0	File No. E258204

※ Pad color can be adjustable upon request